

Form PTO-1449 (modified) List of Patents and Publications For Applicant's Information Disclosure Statement (Use several sheets if necessary)			ATTY. DKT. NO. 5181-83401 APPLICANT: Howard L. Davidson FILING DATE: Herewith			SERIAL NO. Unknown GROUP: Unknown		
U.S. PATENT DOCUMENTS								
EXAM. INITIALS	REF. DES.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE	
11m	A1	4,742,024	05/1988	Sugimoto et al.				
	A2	5,300,272	04/1994	Simandl et al.				
	A3	5,484,964	01/1996	Dawson et al.				
	A4	5,783,316	07/1998	Colella et al.				
	A5	6,011,313	01/2000	Shangguan et al.				
	A6	6,033,506	03/2000	Klett				
	A7	6,153,060	11/2000	Pommer et al.				
	A8	6,168,980	01/2001	Yamazaki et al.				
	A9	6,181,006	01/2001	Ahl et al.				
	A10	6,195,256	02/2001	Tiziani et al.				
	A11	6,197,646	03/2001	Goto et al.				
✓	A12	6,198,143	03/2001	Ohsaki et al.				
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
	A13	Harish Mavoori, Ainissa G. Ramirez, and Sungho Jin, "Universal solders for direct and powerful bonding on semiconductors, diamond, and optical materials" Appl. Phys. Lett. 78(19), May 2001, pp 2976-2978.						

EXAMINER: 

DATE CONSIDERED: 2-6-4

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the patent owner.

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List of Patents and Publications

For Applicant's Information

Disclosure Statement

(Use several sheets if necessary)

ATTY. DKT. NO. 5181-83401

SERIAL NO. 10/600,945

APPLICANT: Howard L. Davidson

ART NO.: 2812

FILING DATE: June 20, 2003

U.S. PATENT DOCUMENTS

EXAM. INITIALS	REF. DES.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

1m	B1	James Klett, "High Thermal Conductivity, Mesophase Pitch-Derived Graphitic Foams" <i>Composites In Manufacturing</i> , The Composites Manufacturing Association of the Society of Manufacturing Engineers, Fourth Quarter 1999, Vol. 15, No. 4.
1m	B2	James Klett et al., "Graphitic Foam Thermal Management Materials for Electronic Packaging" <i>SAE Technical Paper Series</i> , 2000-01-1576.
1m	B3	James Klett et al., "Heat Exchangers for Heavy Vehicles Utilizing High Thermal Conductivity Graphite Foams" <i>SAE Technical Paper Series</i> , 2000-01-2207.
1m	B4	R.W. Garman et al., "Thermal Performance of a Graphite Foam Material with Water Flow for Cooling Power Electronics" <i>PCIM 2001 Power Electronics Conference</i> August 11-13, 2001, pp. 178-187.
1m	B5	James Klett et al., "Thermal Management Solutions for Utilizing High Thermal Conductivity Graphite Foams" <i>SAMPE Technical Paper Database</i> , SAMPE 2000-Long Beach, CA May 21-25, 2000.
1m	B6	James Klett et al., "Carbon Foam for Electronics Cooling" <i>Automotive Propulsion Materials</i> , 2001 Annual Progress Report, U.S. Department of Energy, October 2001, pp. 19-25.
1m	B7	James Klett et al., "Carbon Foam Thermal Management Materials for Electronic Packing" <i>Automotive Propulsion Materials</i> , 2000 Annual Progress Report, U.S. Department of Energy, October 2000, pp. 7-11.

EXAMINER: *1m*

DATE CONSIDERED: 2-6-4

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